



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of

KONISHI et al. Atty. Ref.: 829-615; Confirmation No. 3539

Appl. No. 10/659,261 TC/A.U. 1722

Filed: September 11, 2003 Examiner: Davis, Robert B.

For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR SEMICONDUCTOR  
DEVICES USING THE SAME

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February 15, 2006

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT IN RCE**

Responsive to the Official Action dated November 17, 2005, please amend the  
above-identified application as follows: